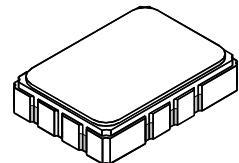


- **Designed for SDARS IF Receiver**
- **Low Insertion Loss**
- **5.0 X 7.0 mm Surface-Mount Case**
- **Differential Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**



SF1143B

315.00 MHz
SAW Filter



SMP-03

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Max Soldering Profile	265°C for 10 s	

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_C			315.000		MHz
Passband	Insertion Loss at f_C	1		15.1	17.0	dB
	1dB Passband	BW_1	± 6.35	± 7.05		MHz
	Fast Amplitude Ripple over $f_C \pm 6.35$ MHz			1.0		dB_{P-P}
	Group Delay Variation over $f_C \pm 6.35$ MHz	GDV		23	200	ns_{P-P}
Rejection	100 to $f_C - 10.3$ and $f_C + 10.3$ to $f_C + 100$ MHz		40	TBD		dB
Operating Temperature Range	T_A	1	-40		+85	°C
Differential Input and Output Impedance				250 ohms		
Case Style						SMP-03 7 x 5 mm Nominal Footprint
Lid Symbolization (YY=year, WW=week, S=shift) See note 4		6				RFM SF1143B YYWWS

Electrical Connections

Connection	Terminals
Port 1 Hot	10
Port 1 Ground Return	1
Port 2 Hot	5
Port 2 Ground Return	6
Case Ground	All Others

NOTES:

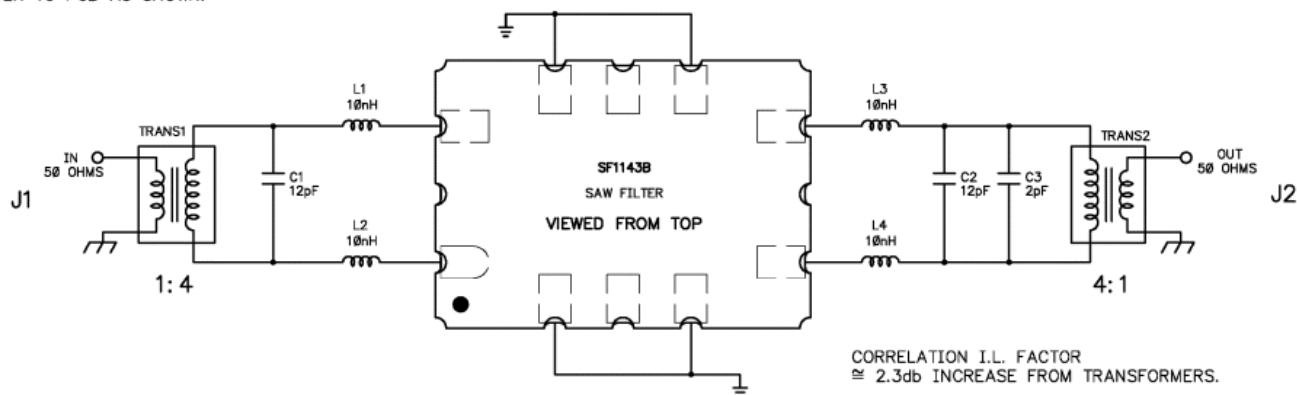
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_C .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.
10. Electrostatic Sensitive Device. Observe precautions for handling.



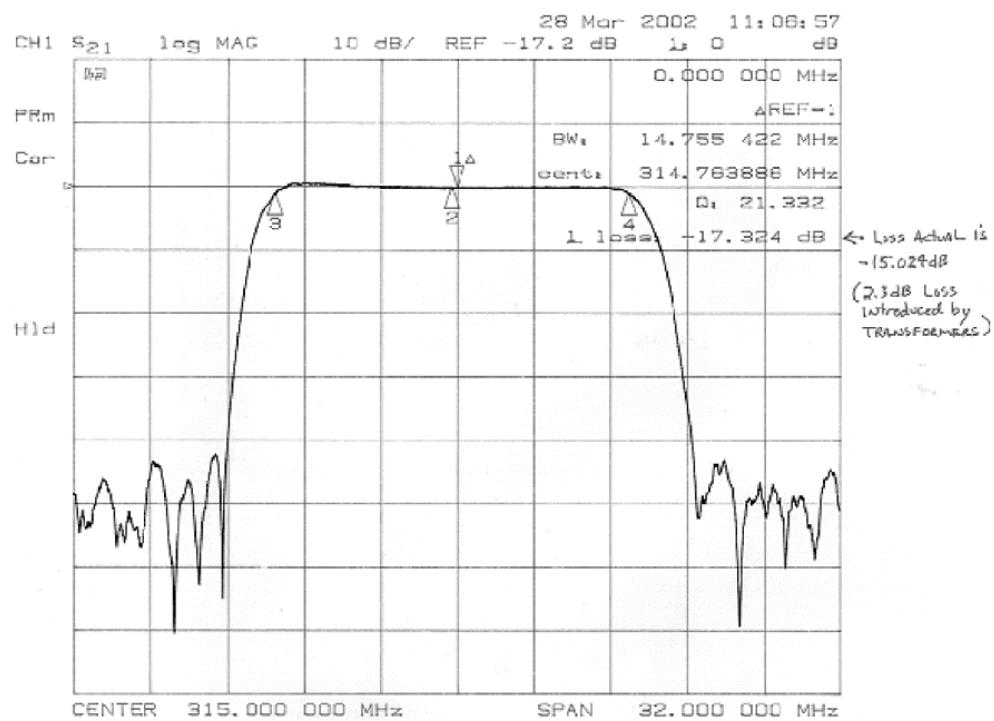
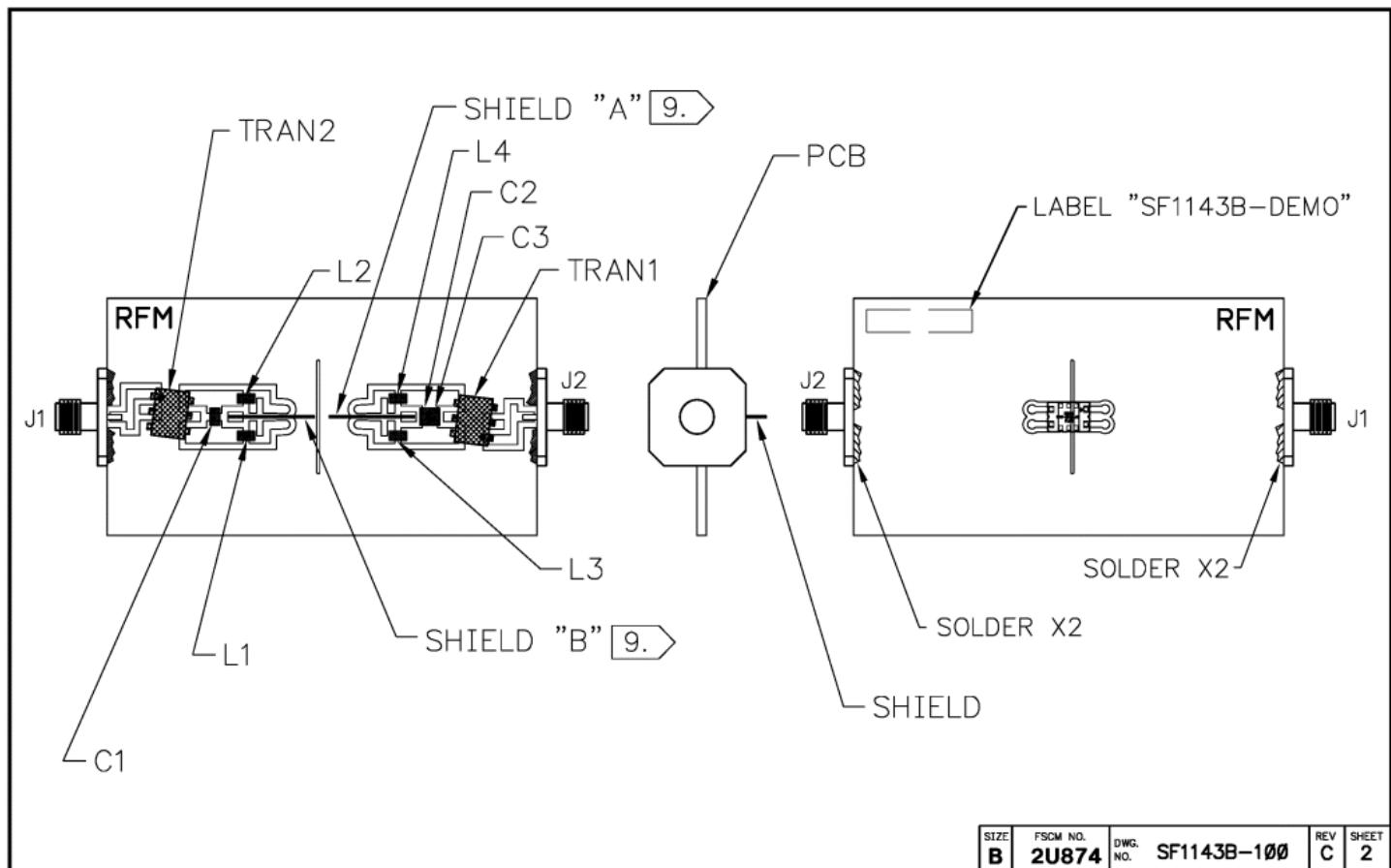
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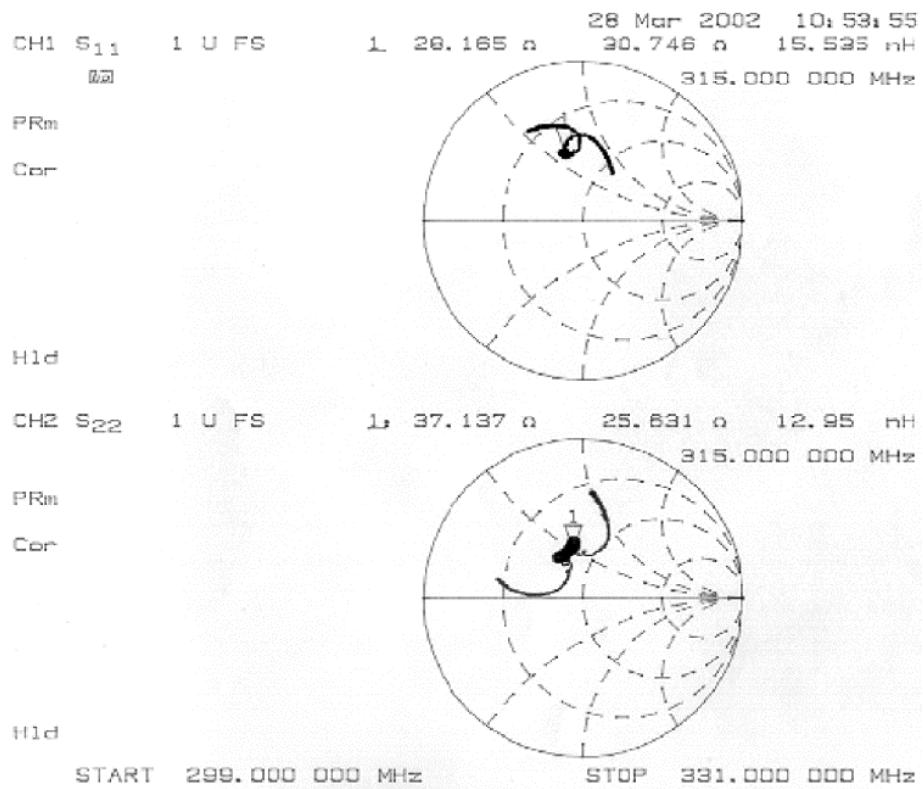
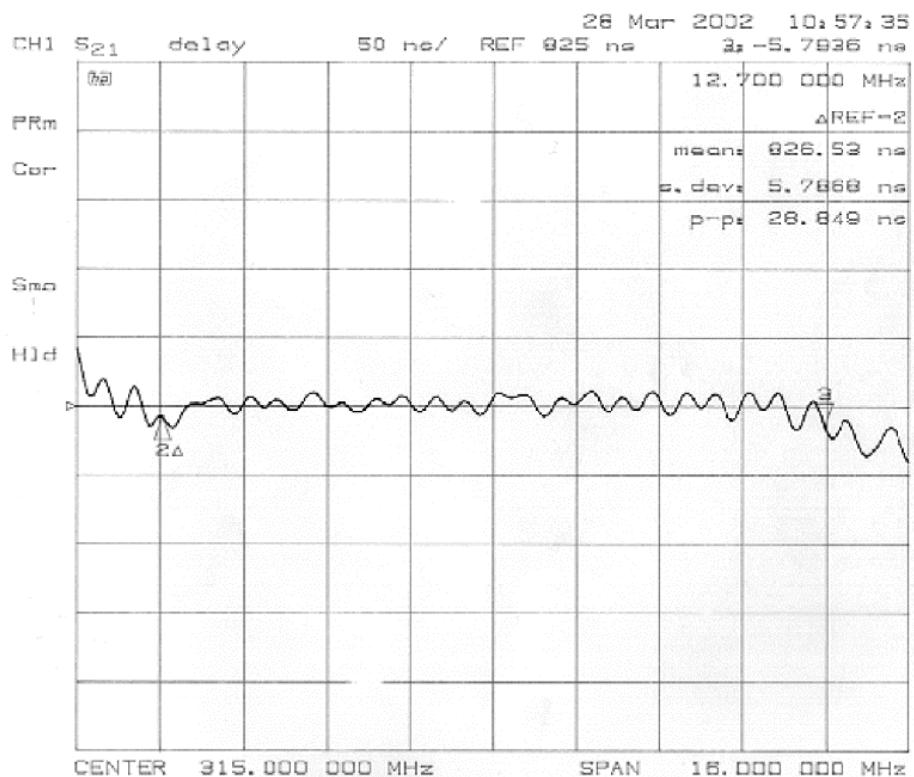
- ~~SOLDER "TAPE" 2 PLACES ONTO COMPONENT SIDE OF PCB AS SHOWN.~~
- USE A WRIST STRAP WHEN SOLDERING TRANS 1, AND TRANS 2 TO PCB. (CUT LEADS .07 IN.)
- MOUNT AND SOLDER ALL COMPONENTS ON PCB.
- CUT CENTER CONDUCTORS FROM J1 AND J2 TO .10 IN.
- MOUNT J1 AND J2 AS SHOWN (SOLDER BACKSIDE ALSO).
- LABEL DEMO BOARD ACCORDINGLY.
- MOUNT "FILTER" ON TOPSIDE OF PCB AS SHOWN.
- ~~CUT ETCH UNDER COMPONENT~~
- ~~CUT SHIELD IN TWO PIECES..."SHIELD A" AND "SHIELD B". SOLDER TO PCB AS SHOWN.~~

REV	ECN	DESCRIPTION	DATE
A	9194	INITIAL RELEASE	22nov00
B	10654	REVISED	30apr02
C	11075	REVISED	20nov02

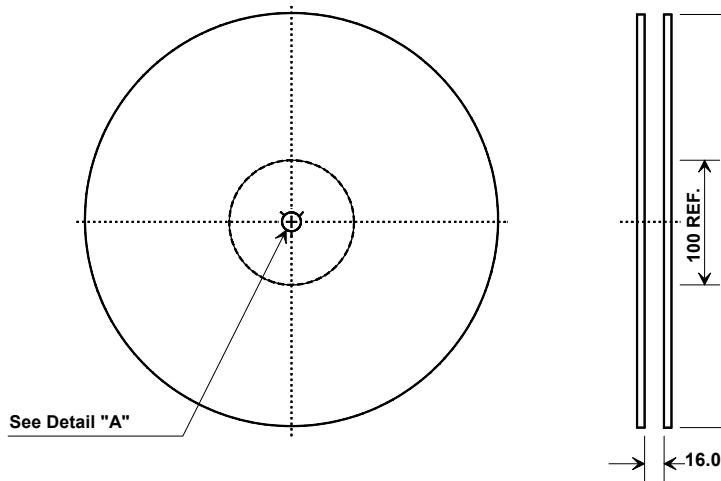


TITLE ASSY DIAGRAM, SF1143B-DEMO, S, TD			
SIZE	FSM NO.	DWG. NO.	REV
B	2U874	SF1143B-100	C 1/2

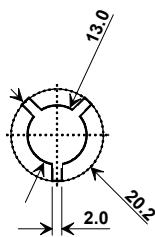




Tape and Reel Specifications

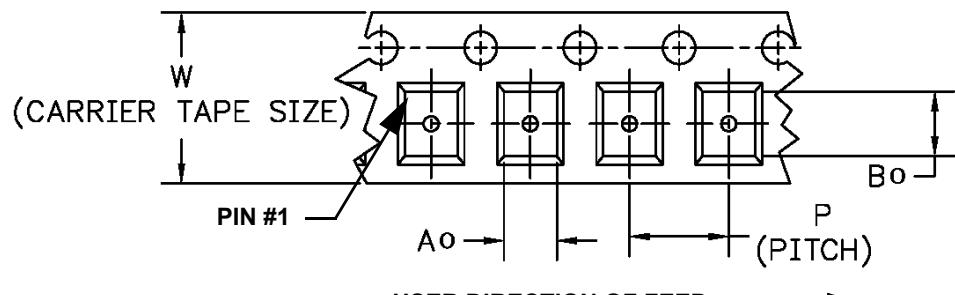
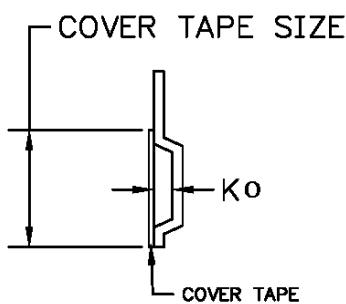


"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000



COMPONENT ORIENTATION and DIMENSIONS

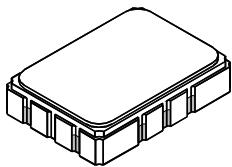
Carrier Tape Dimensions		Tolerance
A_o	5.5 mm	± 0.1 mm
B_o	7.5 mm	± 0.1 mm
K_o	2.0 mm	± 0.1 mm
Pitch	8.0 mm	± 0.1 mm
W	16.0 mm	± 0.2 mm



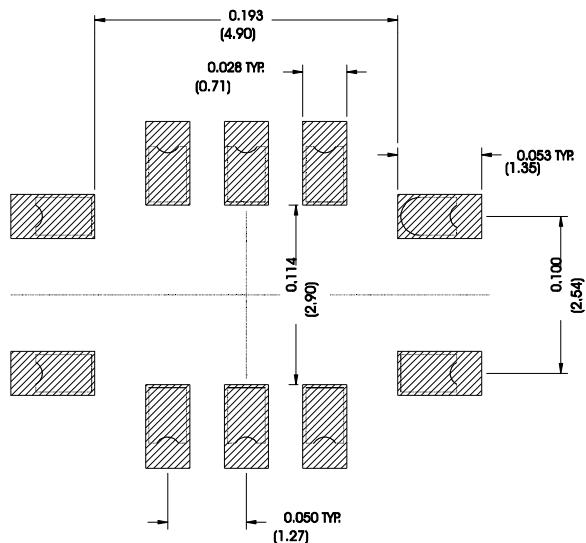
SMP-03 Case

10-Terminal Ceramic Surface-Mount Case

7 x 5 mm Nominal Footprint



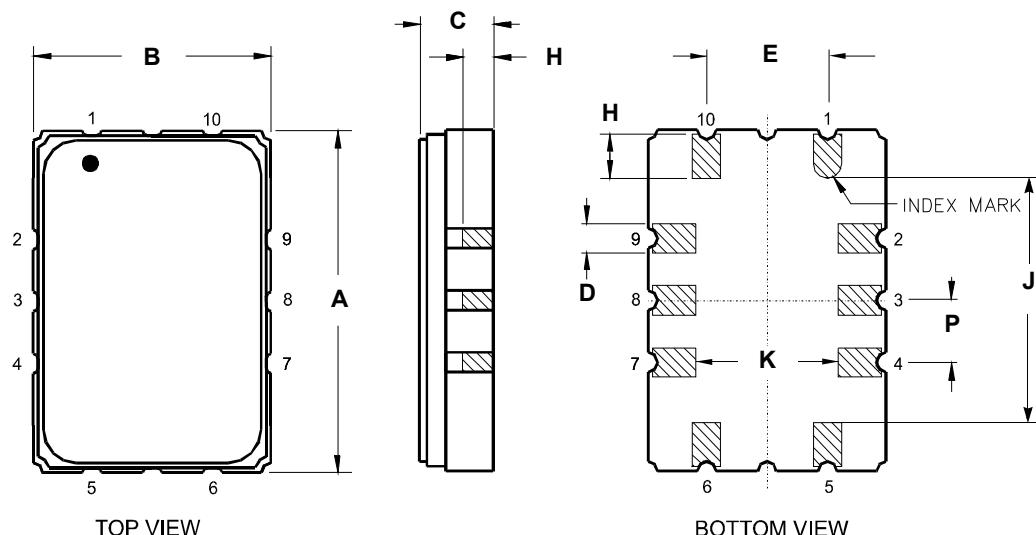
Recommended PCB Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 μ inches (76.2-152 μ m) over 80-200 μ inches (203-508 μ m) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μ inches Thick
Body	Al_2O_3 Ceramic
Pb Free	

Electrical Connections		
	Connection	Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot



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